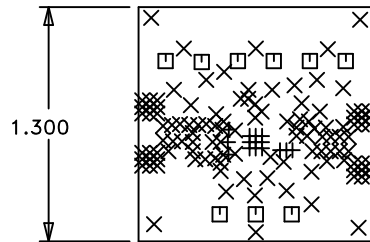


DO NOT SCALE PRINT

REVISION				
ZONE	LTR	DESCRIPTION	DATE	APPROVED
	1	ENGINEERING RELEASE	12/28/09	V. LY



HITTITE MICROWAVE
PCB #128691-1
DRILL DRAWING

SIZE	QTY	SYM	PLATED	TOL
10	15	+	YES	+/-3
14	116	X	YES	+/-3
63	9	□	YES	+/-3

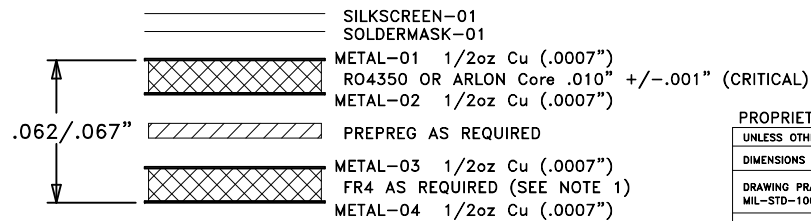
NOTES:

UNLESS OTHERWISE SPECIFIED

1. MATERIAL: MULTILAYER. OVERALL STACKUP AS SHOWN. TYPE ROGERS 4350 OR ARLON 25FR, HALF OUNCE COPPER BOTH SIDES. FR4 TO BE USED AS FILLER TO MEET CRITICAL OVERALL THICKNESS.
2. FINISH: GOLD PLATE PER ASTM B-488, TYPE III, CODE A, 8 TO 40 MICROINCHES, OVER NICKEL PER QQ-N-290, 100 MICROINCHES MINIMUM.
3. PLATED THRU HOLES: .001" MINIMUM WALL THICKNESS.
4. HOLE SIZES AND POSITIONS PER ARTWORK AND/OR DRILL FILE.
5. ALL HOLES TO BE LOCATED WITHIN ± 0.003 " OF THE CENTER OF THE PAD OR OTHER TRUE POSITION.
6. FRONT TO BACK REGISTRATION ± 0.003 " MAX.
7. BOARD WARPAGE: < 0.010 " PER LINEAR INCH.
8. SILKSCREEN TOPSIDE ONLY WITH WHITE EPOXY INK.
9. PLATING THICKNESS $.002 \pm 0.0005$ FOR METAL-01 AND METAL-04.
10. SOLDERMASK: LPI SOLDERMASK TOP SIDE. COLOR: GREEN REGISTRATION: ± 0.004 MAX.
11. REMOVE METAL BURRS FROM EDGE OF PCB AFTER PANEL SEPARATION.
12. ARTWORK IS 1:1. VENDOR TO ADJUST FOR ETCH FACTOR.
13. "SIZE" IN DRILL LEGEND IS IN MILS AND REFERS TO FINISHED HOLE SIZE.
14. MANUFACTURE PER IPC-6012 CLASS 2.

UNLESS OTHERWISE SPECIFIED

15. CRITICAL LINE WIDTH = $.016 \pm 0.001$ ADJUST PROCESS TO ACHIEVE WIDTH.



LAYER STACKUP

PROPRIETARY TO HITTITE MICROWAVE CORPORATION

UNLESS OTHERWISE SPECIFIED:	
DIMENSIONS ARE IN INCHES (MM)	
DRAWING PRACTICES PER MIL-STD-100	

TOLERANCES:	
.XX	+/- 0.010
.XXX	+/- 0.005
.XXXX	+/- 0.002
ANGLES	+/- .5 DEG

DWN BY:
V. LY 12/17/09

ENGINEER:
A. EKEN 12/18/09



HITTITE MICROWAVE CORPORATION
20 Alpha Road Chelmsford, MA 01824

TITLE
PCB, EVAL
HMC5633LP4

SIZE	CODE ID NO.	DRAWING NO.	REV
A	1CN88	128691	1
SCALE: NONE		WT	SHEET 1 of 1